

SSC8021GN1

P-Channel MOSFET with ESD Protection

Features \triangleright

VDS	VGS	RDSON Typ.	ID	ESD
2014	±12V	0.45R@-4V5	1 A	0.5kV
-20V	±12V	0.6R@-2V5	-1A	

Description \triangleright

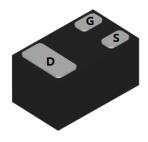
This device particularly suits low voltage applications such as portable equipment, power management and other battery powered circuits, and low in-line power dissipation are needed in a very small outline surface mount package. The product does not contain Rohs substances such as lead and halogen.

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Pin configuration

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Bottom view



Applications \geq

- Load Switch
- Portable Devices
- Signal Drive

Ordering Information \geq

Device	Package	Shipping
SSC8021GN1	DFN1006-3L	10K/Reel



Marking



> Absolute Maximum Ratings(T_A=25[°]C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V _{DSS}	Drain-to-Source Voltage	-20	V
V _{GSS}	Gate-to-Source Voltage	±12	V
Ι _D	Continuous Drain Current ^a	-1	А
I _{DM}	Pulsed Drain Current ^b	-3	А
PD	Power Dissipation ^c	0.45	W
P _{DSM}	Power Dissipation ^a	0.2	W
TJ	Operation junction temperature	-55 to 150	°C
T _{STG}	Storage temperature range	-55 to 150	°C

> Thermal Resistance Ratings($T_A=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Maximum	Unit	
R _{θJA}	Junction-to-Ambient Thermal Resistance ^a	625	°C (M	
Rejc	Junction-to-Case Thermal Resistance	277	°C/W	

Note:

- a. The value of R_{BJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper,in a still air environment with T_A=25°C. The value in any given application depends on the user is specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

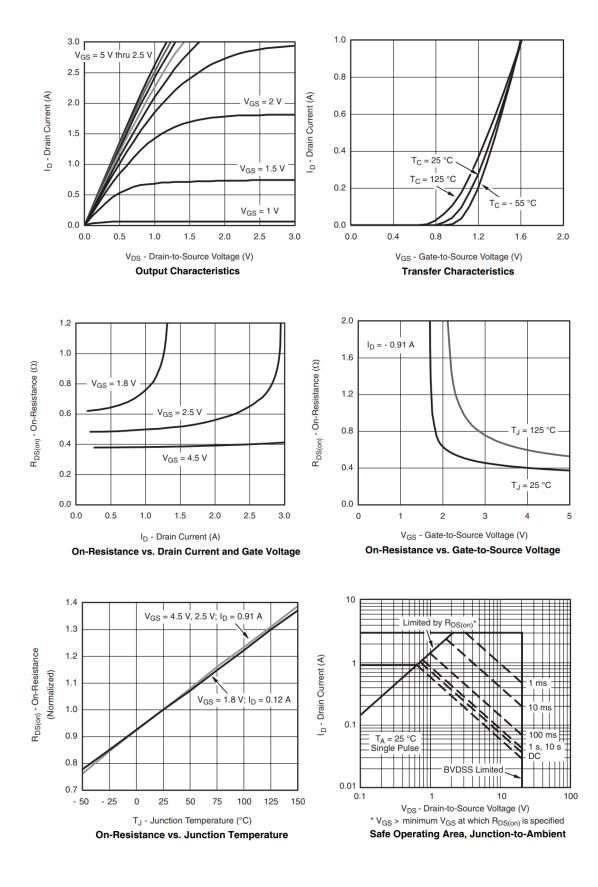


Electronics Characteristics(T_A=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур.	Мах	Unit
V _{(BR)DSS}	Drain-Source	VGS=0V, ID=-250uA	-20			V
	Breakdown Voltage					-
$V_{GS \ (th)}$	Gate Threshold Voltage	VDS=VGS, ID=-250uA	-0.4	-0.7	-1	V
	Drain Course On	VGS=-4.5V, ID=-0.5A		450	650	
R _{DS(on)}	Drain-Source On- Resistance	VGS=-2.5V, ID=-0.3A		600	900	mR
	Resistance	VGS=-1.8V, ID=-0.1A		800	1500	
I _{DSS}	Zero Gate Voltage Drain Current	VDS=-16V, VGS=0V			-1	uA
I _{GSS}	Gate-Source leak current	VGS=±10V, VDS=0V			±10	uA
G _{FS}	Transconductance	VDS=-5V, ID=-0.5A		1		S
V _{SD}	Forward Voltage	VGS=0V, IS=-0.15A			-1.3	V
Ciss	Input Capacitance			25		
Coss	Output Capacitance	VDS=-10V, VGS=0V, f=1MHz		12		pF
Crss	Reverse Capacitance			5		
T _{D(ON)}	Turn-on delay time			5		
Tr	Rise time	VGS=-4.5V,		4		no
T _{D(OFF)}	Turn-off delay time	VDS=-10V, RL=20R, RG=3R		12		ns
Tf	Fall time			7		



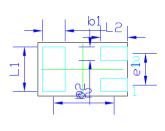
> Typical Characteristics(T_A=25°C unless otherwise noted)





> Package Information





top view

BOTTOM VIEW

COMMON DIMENSION (MM)				
PKG	DFN1006			
REF.	MIN.	NDM.	MAX	
A	0.45	0.50	0.55	
D	0.95	1.00	1.05	
Ш	0.55	0.60	0.65	
b1	0.20	0.25	0.30	
20	0.10	0.15	0.20	
L1	0.45	0.50	0.55	
22	0.25	0.30	0.35	
e1	0.350 BSC			
e۲	0.675 BSC			

<u>SIDE VIEW</u>

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